

## Description

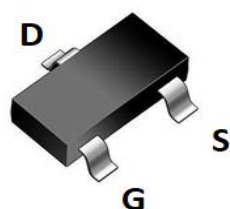
### JMT N-channel Enhancement Mode Power MOSFET

#### Features

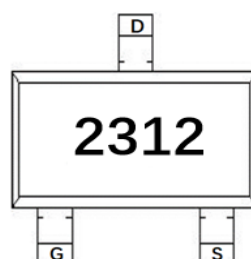
- 20V, 6.8A  
 $R_{DS(ON)} < 21m\Omega @ V_{GS} = 4.5V$   
 $R_{DS(ON)} < 25m\Omega @ V_{GS} = 2.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead Free

#### Applications

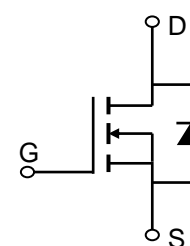
- Load Switch
- PWM Application
- Power Management



SOT-23 Top View



Marking and Pin Assignment



Schematic Diagram

### Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
2312	JMTL2312A	TAPING	SOT-23	7"	3000	120000

### Absolute Maximum Ratings (@ $T_A = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	20	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	6.8
		$T_A = 100^\circ C$	4
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	27	A
$P_D$	Power Dissipation	$T_A = 25^\circ C$	1.3
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(2)</sup>	97	$^\circ C/W$
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ C$



## Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	20	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±12V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.5	0.75	1.0	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 4A	-	16	21	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3A	-	19	25	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 10V, f = 1MHz	-	712	-	pF
C <sub>oss</sub>	Output Capacitance		-	116	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	103	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 4.5V V <sub>DD</sub> = 10V, I <sub>D</sub> = 3A	-	9	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	1.5	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	2.5	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> = 4.5V, V <sub>DD</sub> = 10V I <sub>D</sub> = 3A, R <sub>GEN</sub> = 3Ω	-	5	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	16	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	23	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	7	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	6.8	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	27	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 6.8A	-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> = 3A, di/dt = 100A/us	-	7	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	2	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2. R<sub>θJA</sub> is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB
  3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.

## Typical Performance Characteristics

Figure 1: Output Characteristics

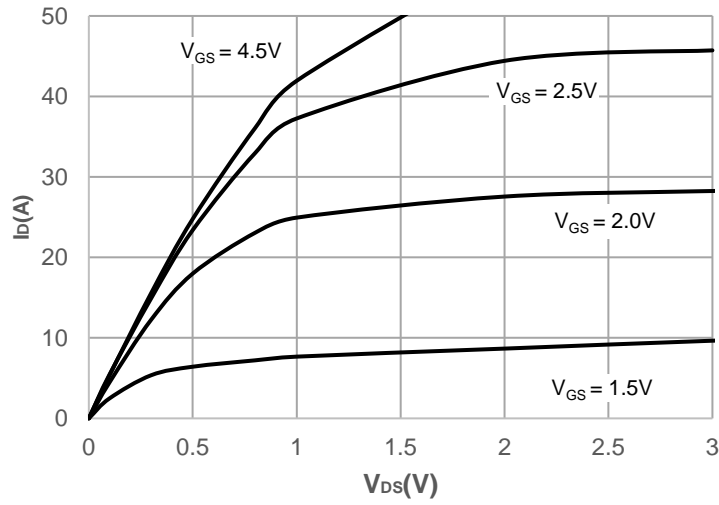


Figure 2: Typical Transfer Characteristics

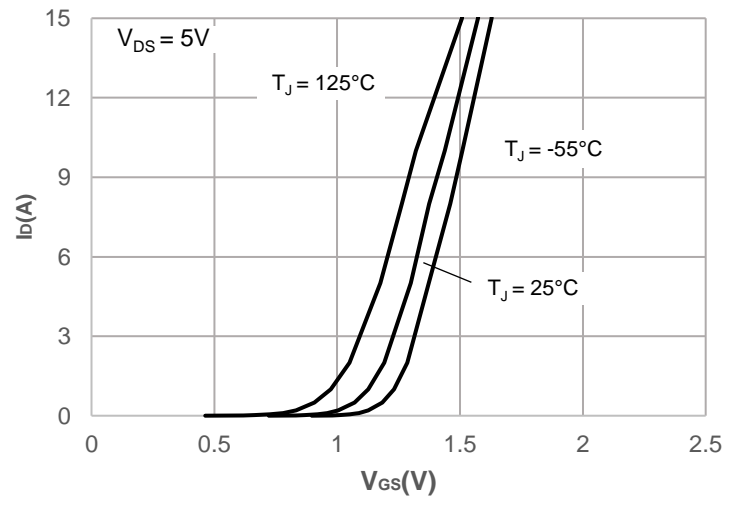


Figure 3: On-resistance vs. Drain Current

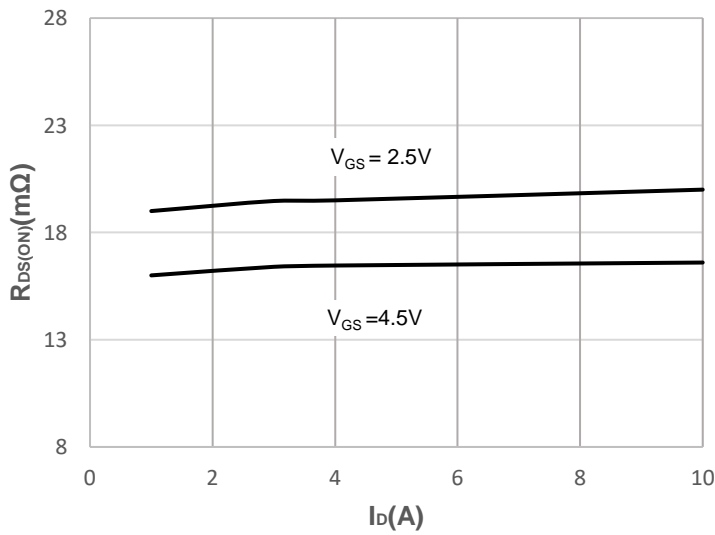


Figure 4: Body Diode Characteristics

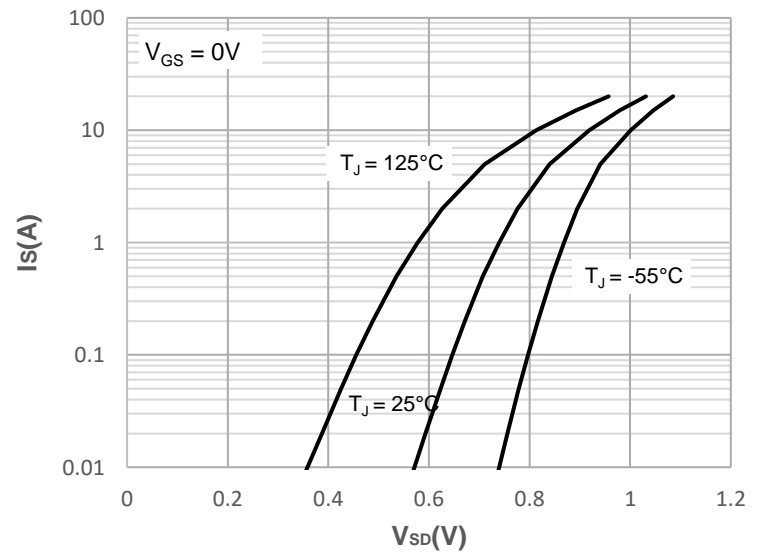


Figure 5: Gate Charge Characteristics

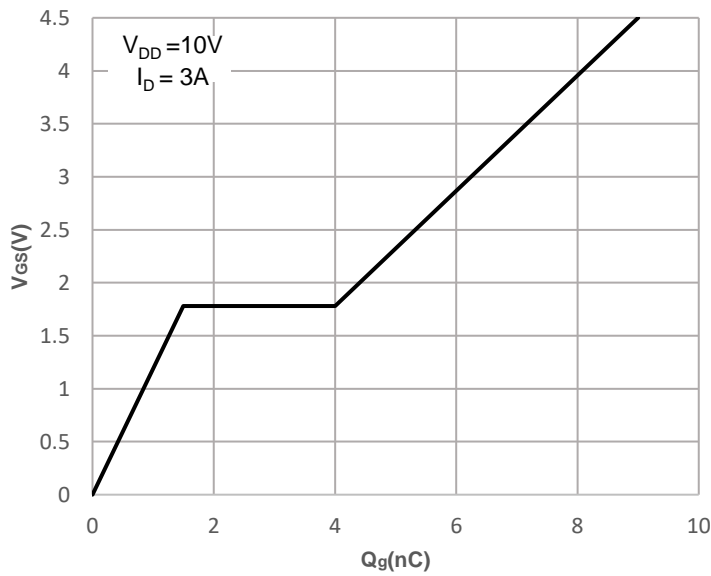
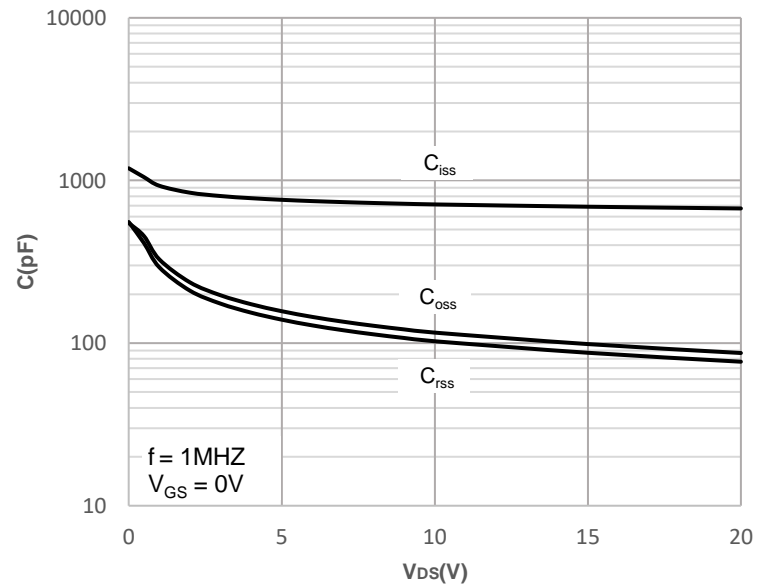


Figure 6: Capacitance Characteristics



## Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

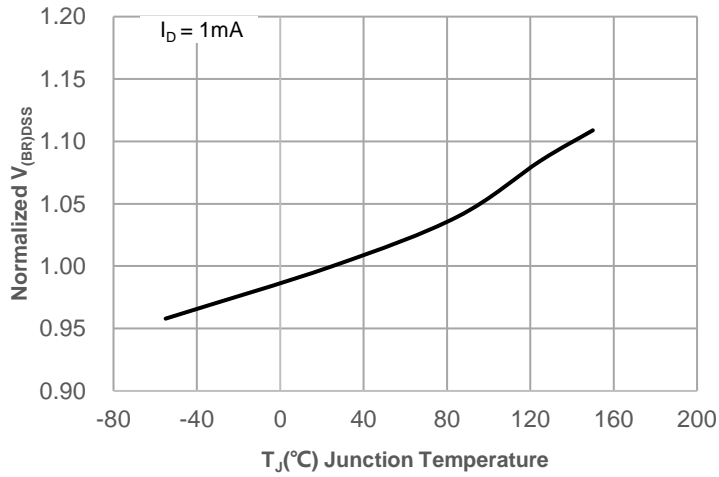


Figure 8: Normalized on Resistance vs. Junction Temperature

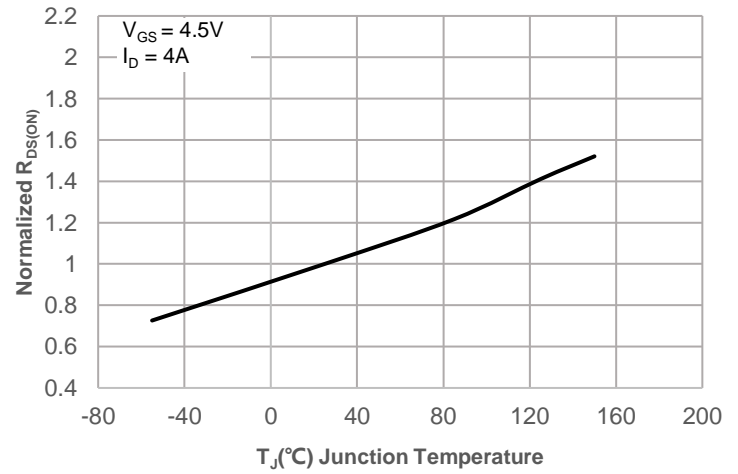


Figure 9: Maximum Safe Operating Area

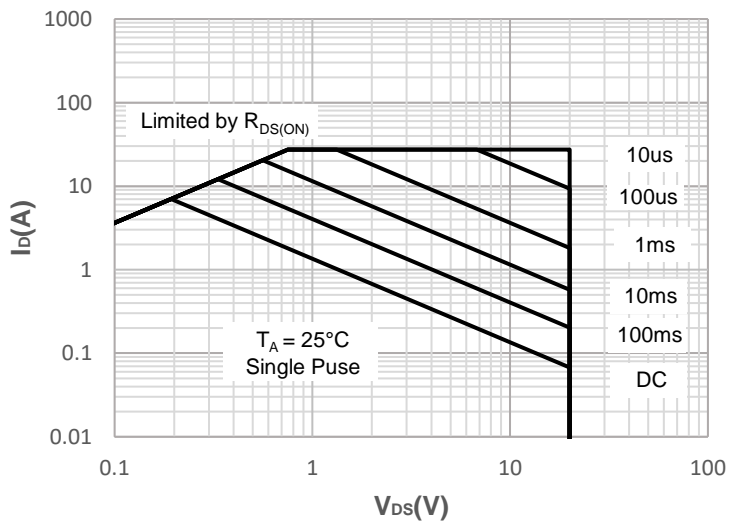


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

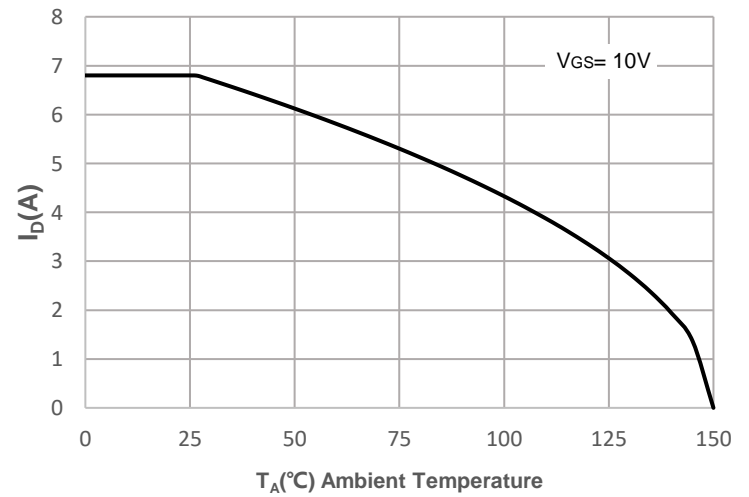


Figure 11: Normalized Maximum Transient Thermal Impedance

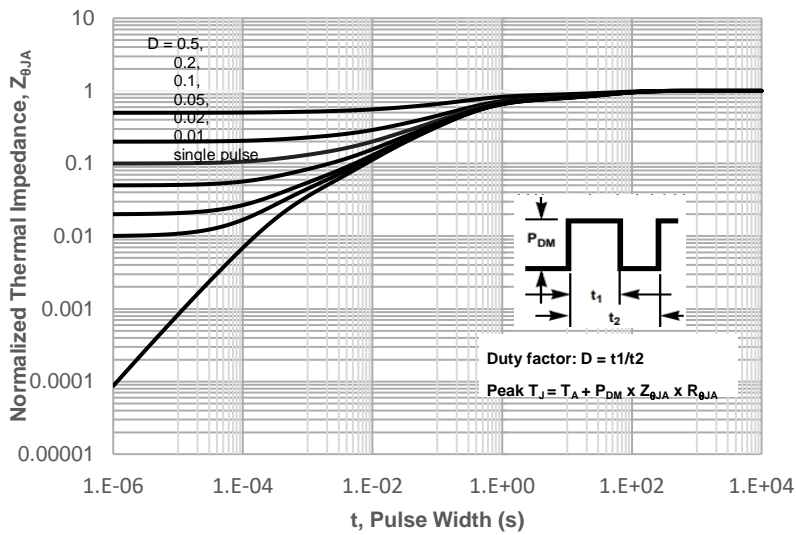
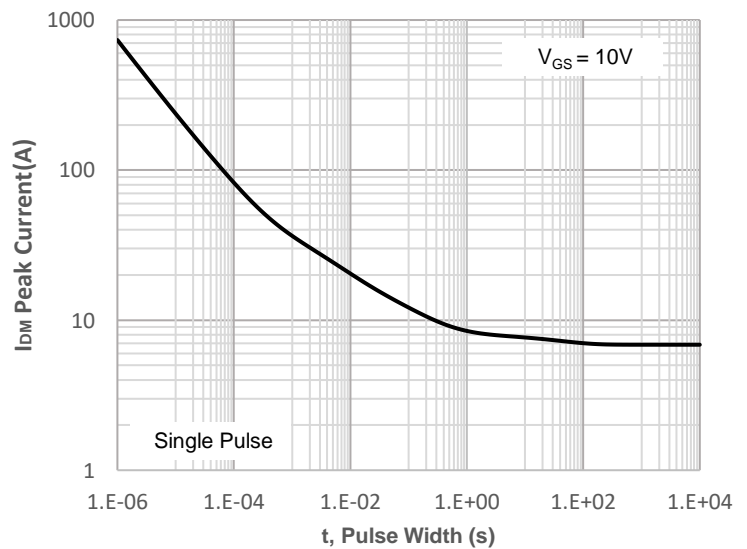


Figure 12: Peak Current Capacity



## Test Circuit

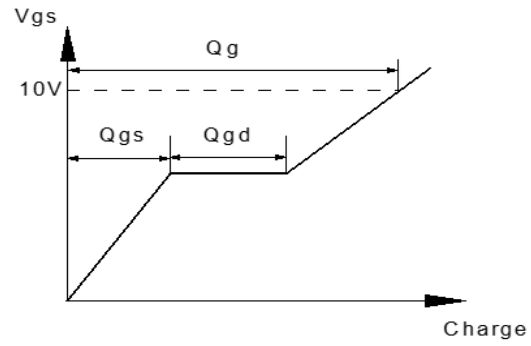
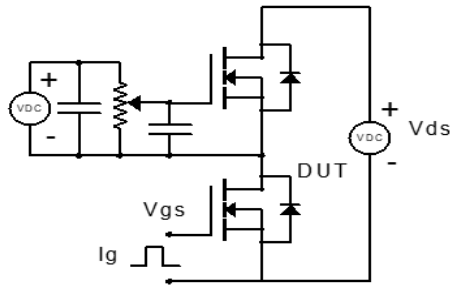


Figure 1: Gate Charge Test Circuit & Waveform

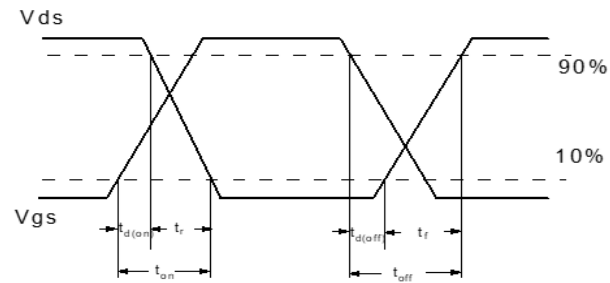
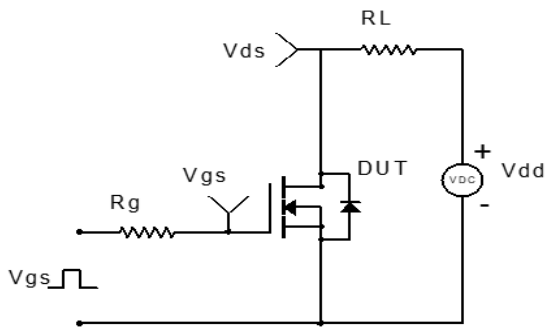


Figure 2: Resistive Switching Test Circuit & Waveform

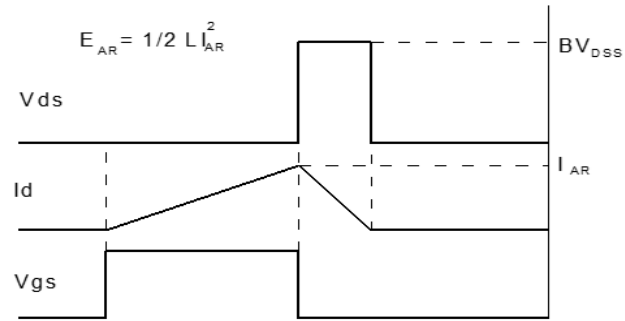
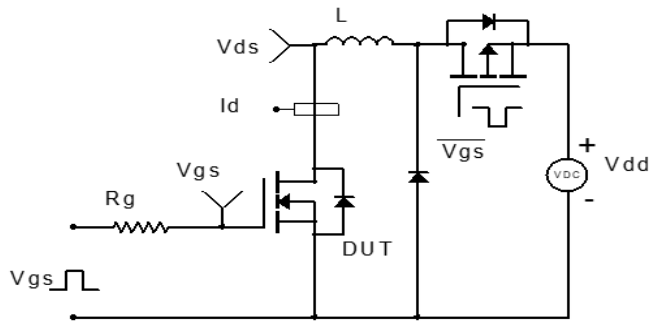


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

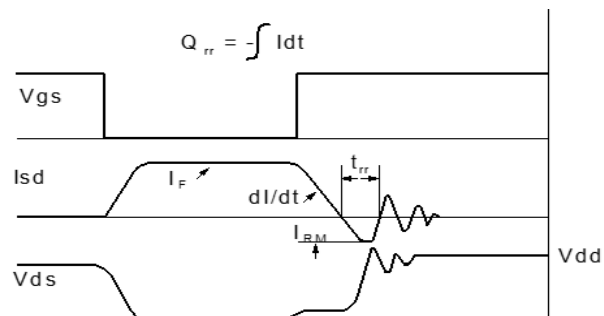
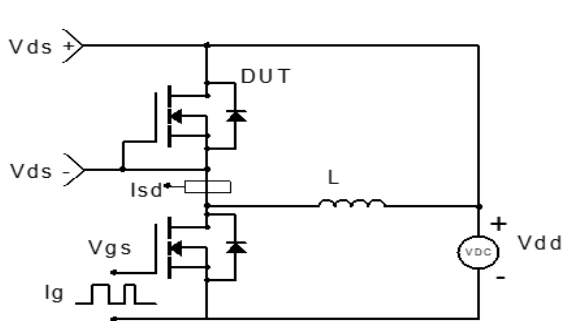
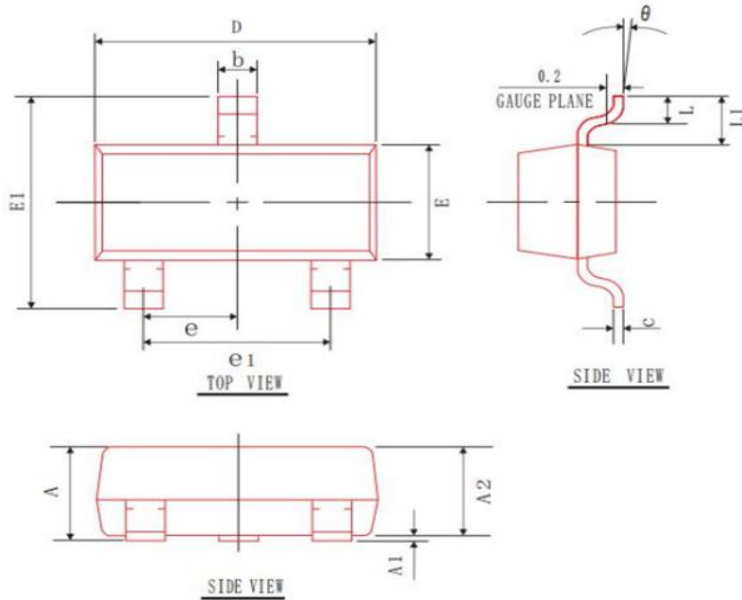


Figure 4: Diode Recovery Test Circuit & Waveform

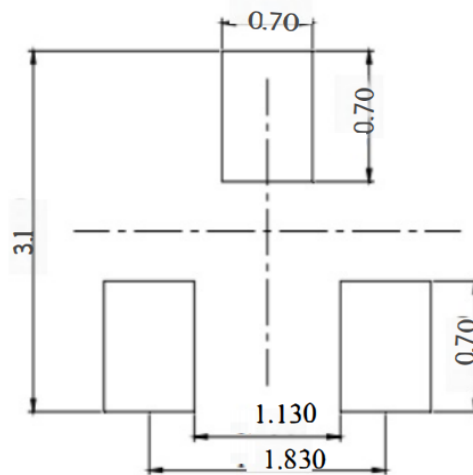
## Package Mechanical Data(SOT-23)



COMMON DIMENSIONS  
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	0.90	1.05	1.20
A1	0.00	0.05	0.10
A2	0.90	1.00	1.10
b	0.30	0.40	0.50
c	0.08	0.10	0.15
D	2.80	2.90	3.00
E	1.20	1.30	1.40
E1	2.30	2.40	2.50
L	0.30	0.40	0.50
$\theta$	0°	5°	10°
L1	0.55 REF		
e	0.95 BSC		
e1	1.90 REF		

### Recommended Footprint



DIMENSIONS:MILLIMETERS

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